

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	48	228/180.1.ccls.	US-PGPUB	OR	ON	2008/06/18 14:17
L2	177	228/180.22.ccls.	US-PGPUB	OR	ON	2008/06/18 14:18
L3	83	228/180.21.ccls.	US-PGPUB	OR	ON	2008/06/18 14:18
L4	53	228/215.ccls.	US-PGPUB	OR	ON	2008/06/18 14:18
L5	15	228/178.ccls.	US-PGPUB	OR	ON	2008/06/18 14:18
L6	8	228/244.ccls.	US-PGPUB	OR	ON	2008/06/18 14:18
L7	338	1 or 2 or 3 or 4 or 5 or 6	US-PGPUB	OR	ON	2008/06/18 14:19
L10	2	7 and ((underfill or underfill\$3 or encapsulant or encapsulat\$3) same (((metal or metallic) same (powder or particle)) or filler) same (gap or space) same (chip or board or substrate))	US-PGPUB	OR	ON	2008/06/18 14:28
L22	309	((connect\$3 or attach\$3 or mount \$3) with (chip or board or substrate) and (underfill or encapsulant or encapsulat\$3) with (particle or metal\$5 or filler) with (gap or space or interval))	US-PGPUB	OR	ON	2008/06/18 14:53

L25	0	22 and (("200."\$2 or "300."\$2 or "400."\$2 or "500."\$2 or "600."\$2 or "700."\$2 or "800."\$2 or "900."\$2) and micron)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/18 14:59
L26	22	((underfill or underfill\$3 or encapsulant or encapsulat\$3) same (((metal or metallic) same (powder or particle)) or filler) same (gap or space) same (chip or board or substrate)).clm.	US-PGPUB	OR	ON	2008/06/18 15:00
L27	2	((solder or ball) same (array or interconnect\$3)) same (underfill or underfill\$3 or encapsulant or encapsulat\$3) same (((metal or metallic) same (powder or particle)) or filler) same (gap or space) same (chip or board or substrate)).clm.	US-PGPUB	OR	ON	2008/06/18 15:02
L29	0	((solder or ball) and (array or interconnect\$3)) and (underfill or underfill\$3 or encapsulant or encapsulat\$3) and (((metal or metallic) and (powder or particle)) or filler) and (gap or	US-PGPUB	OR	ON	2008/06/18 15:06

		space) and (chip or board or substrate) and ("200."\$2 or "300."\$2 or "400."\$2 or "500."\$2 or "600."\$2 or "700."\$2 or "800."\$2 or "900."\$2) and micron)).clm.				
L30	3	((solder or ball) and (array or interconnect\$3)) and (underfill or underfill\$3 or encapsulant or encapsulat\$3) and (((metal or metallic) and (powder or particle)) or filler) and (gap or space) and (chip or board or substrate) and micron)).clm.	US-PGPUB	OR	ON	2008/06/18 15:07

**6/18/2008 3:10:55 PM**

**C:\Documents and Settings\maboagye\My Documents\EAST\Workspaces\10711501  
solder interconnect array with optimal mechanical integrity 228-215 FOAM 10-03-2006.  
wsp**